

FIG. 2

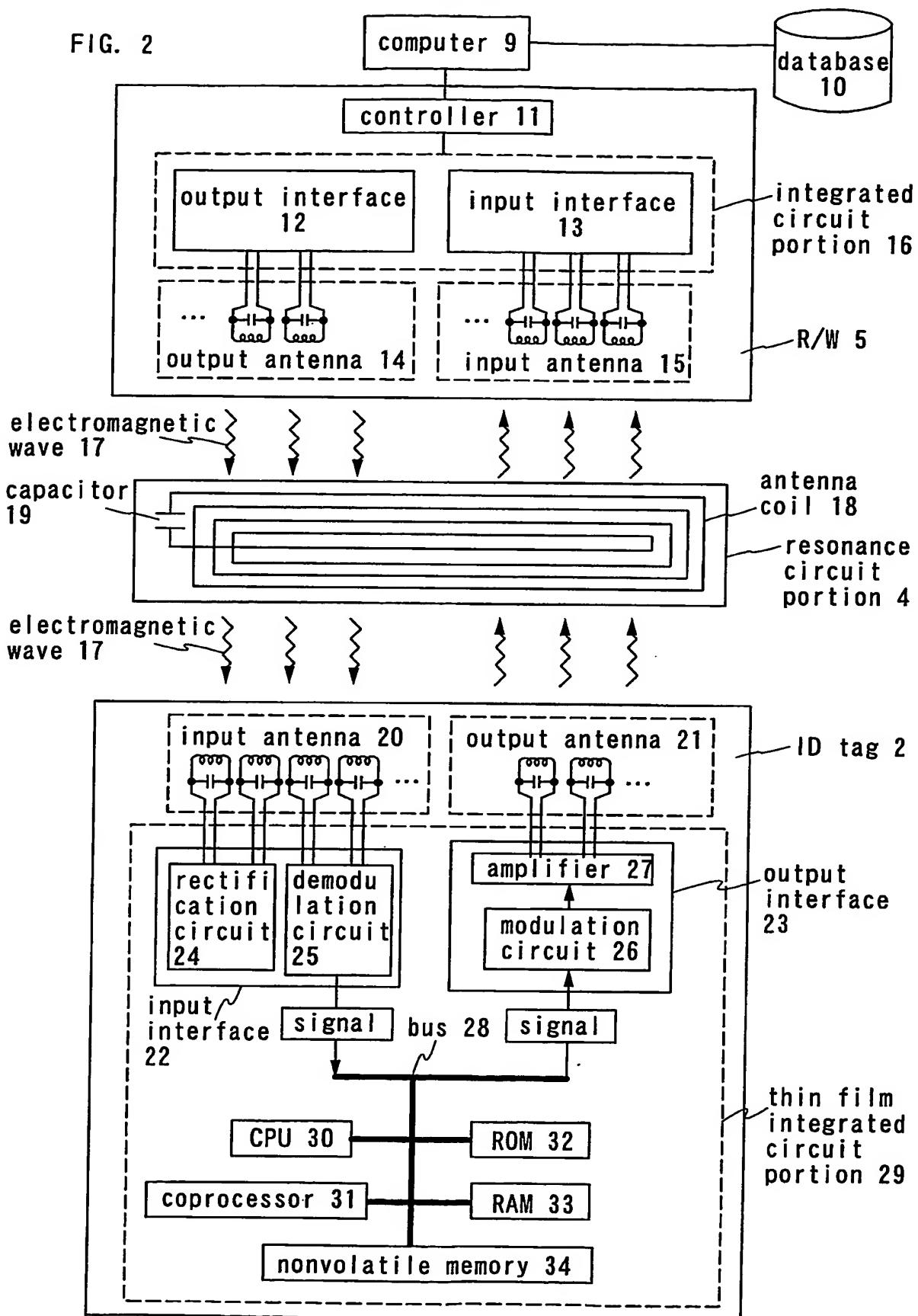


FIG. 3

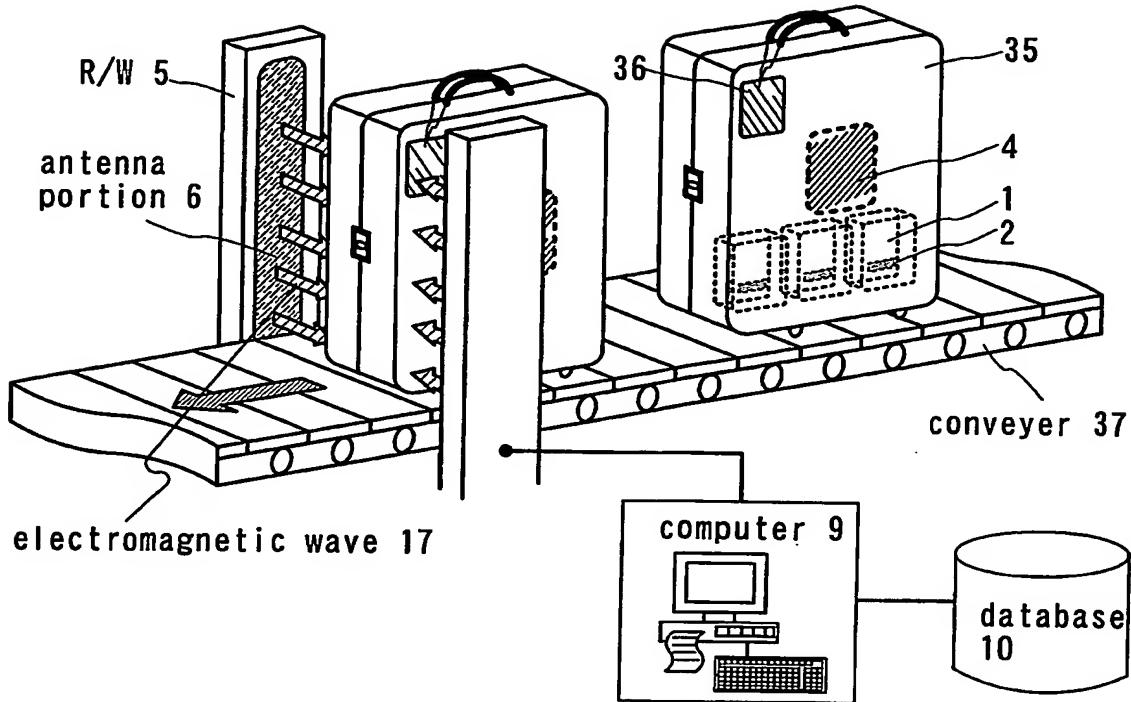
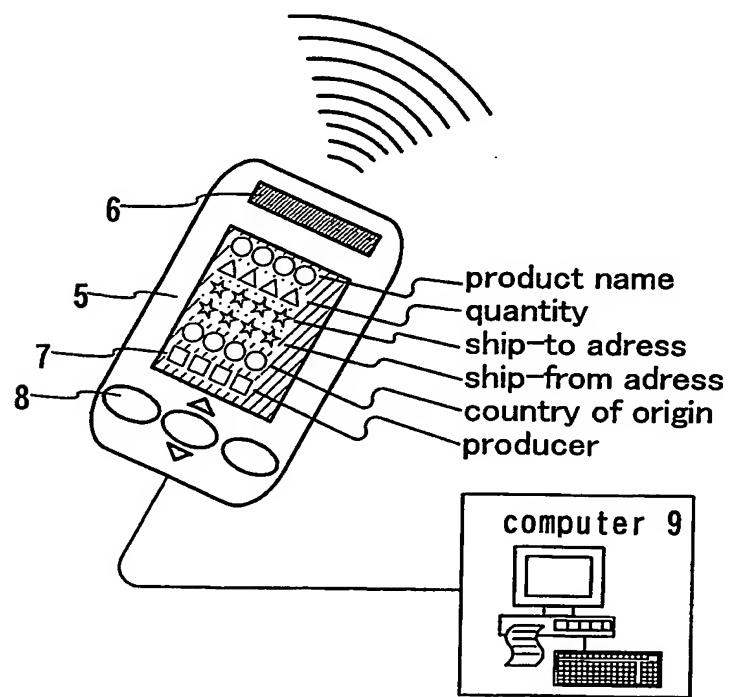
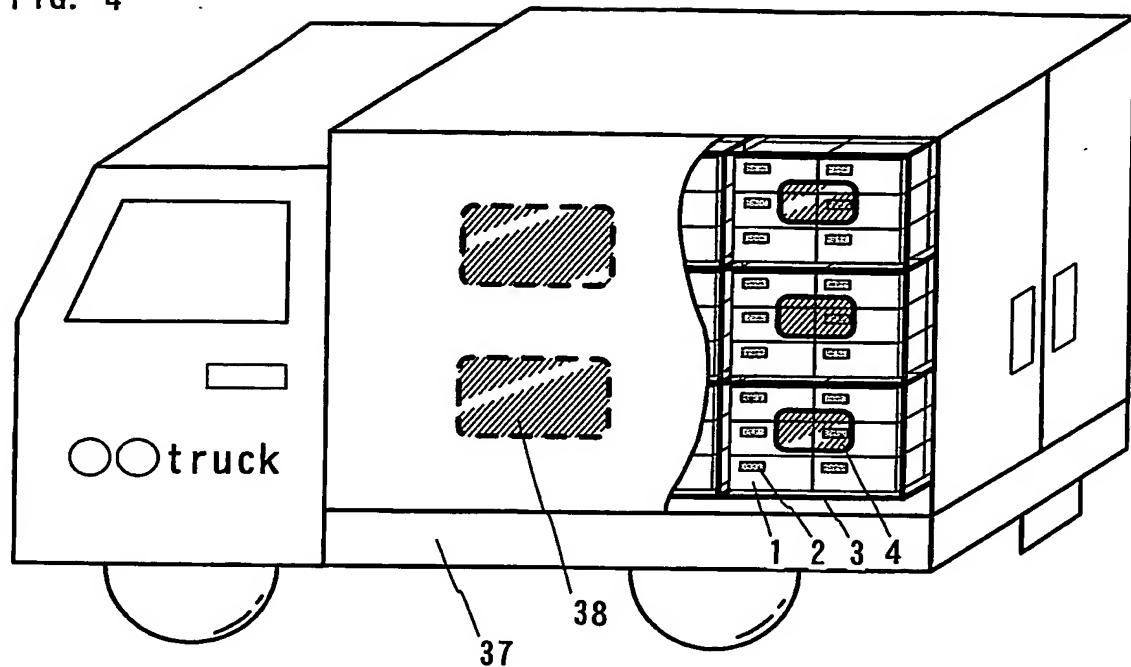


FIG. 4



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FIG. 5A

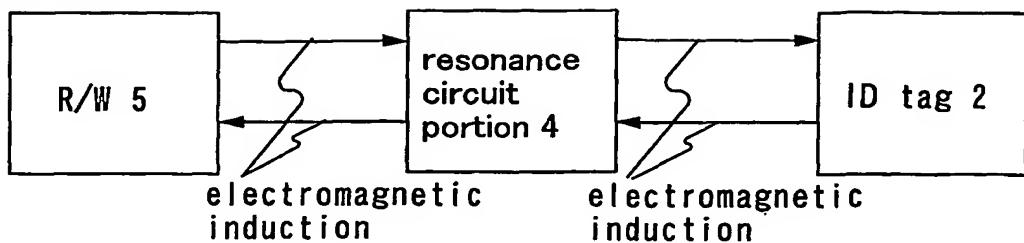


FIG. 5B

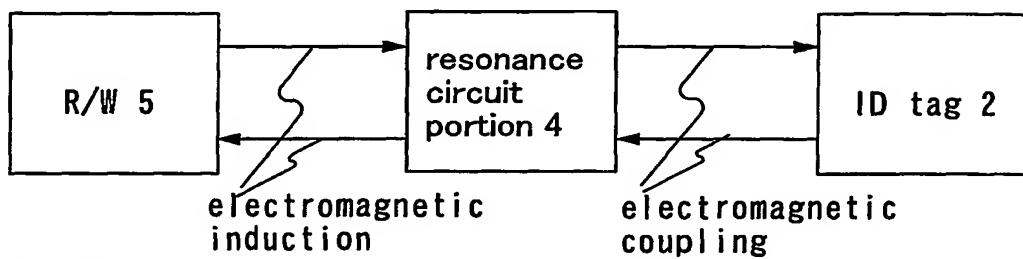
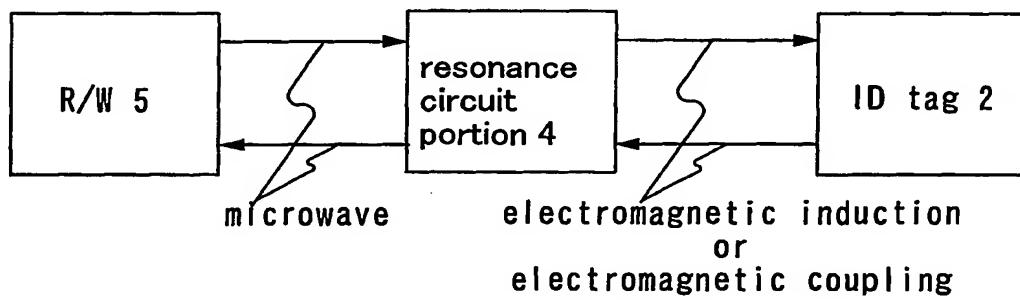


FIG. 5C



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FIG. 6

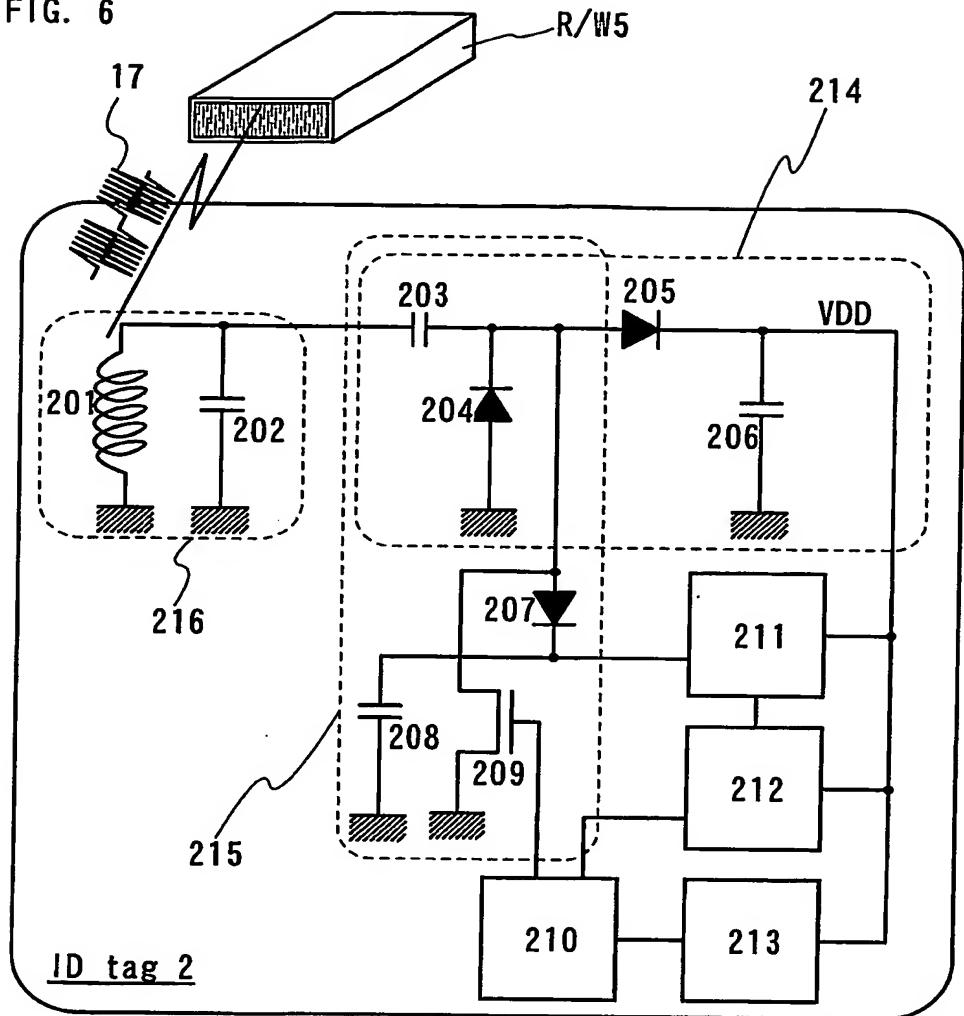


FIG. 7A forming separation layer and protective film

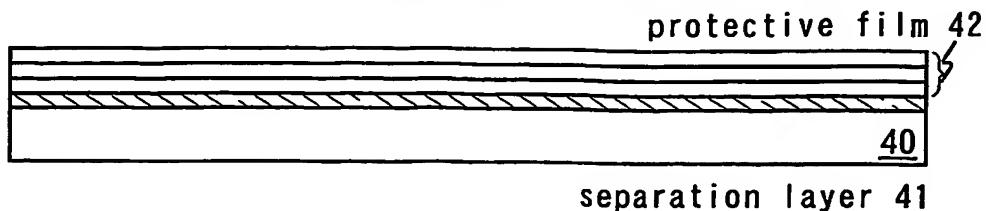


FIG. 7B forming semiconductor film and gate insulating film

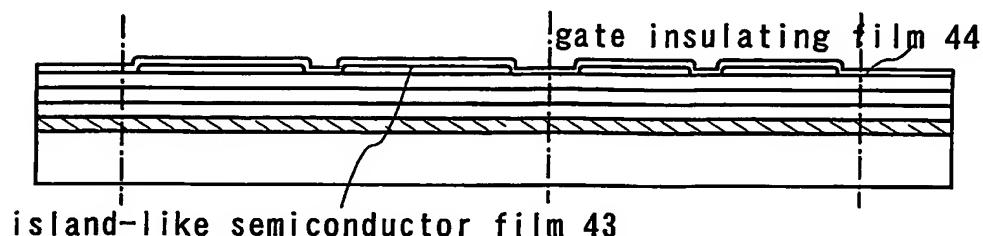


FIG. 7C forming gate electrode

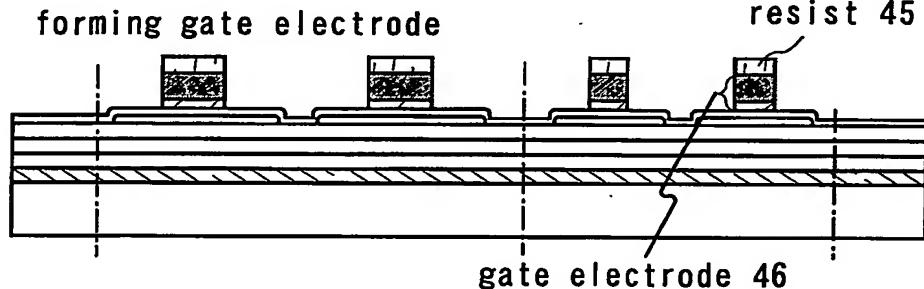


FIG. 7D forming n-type low concentration impurity region

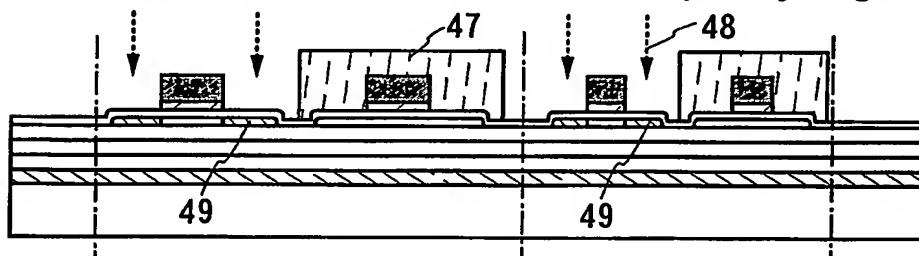


FIG. 7E forming p-type high concentration impurity region

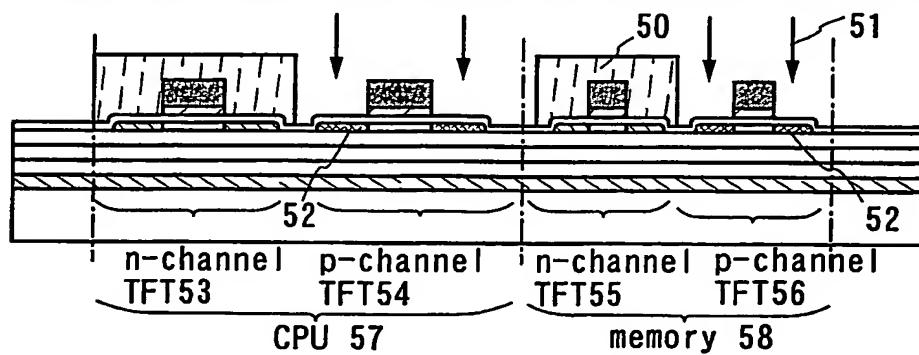


FIG. 8F forming insulatin film

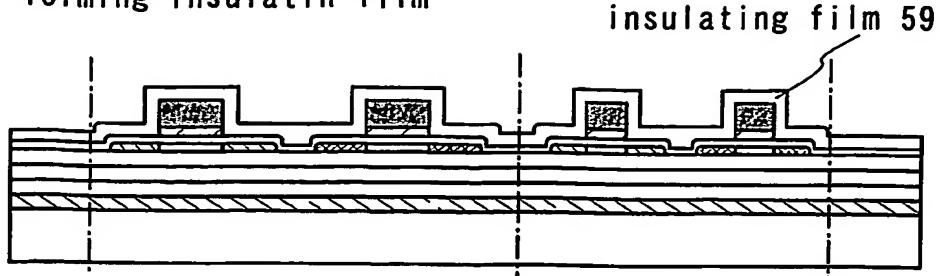


FIG. 8G etchback (forming sidewall)

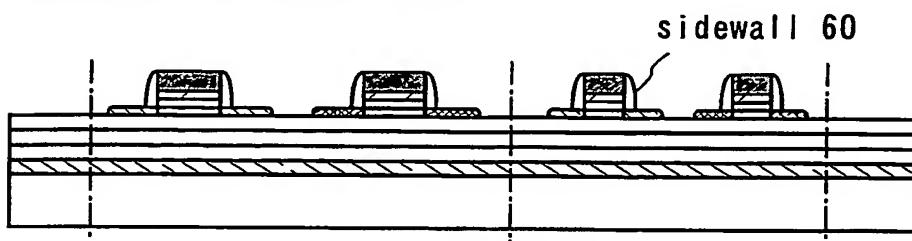


FIG. 8H forming n-type high concentration impurity region

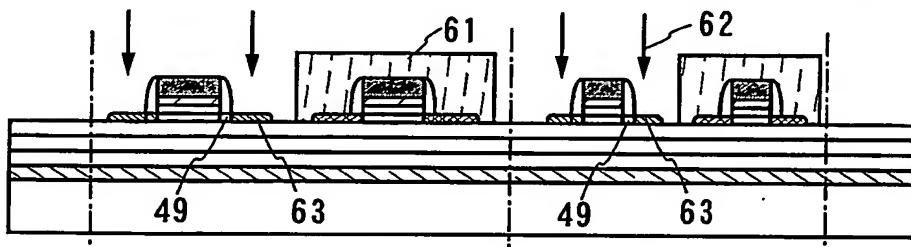


FIG. 8I forming interlayer, protective film and wiring

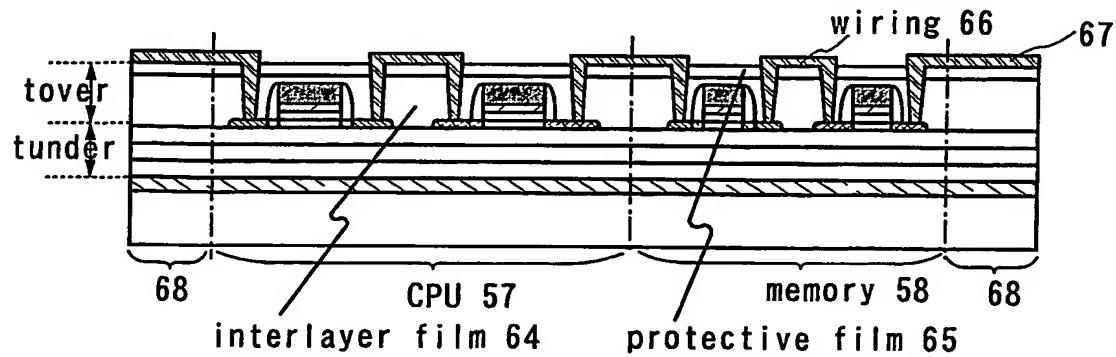
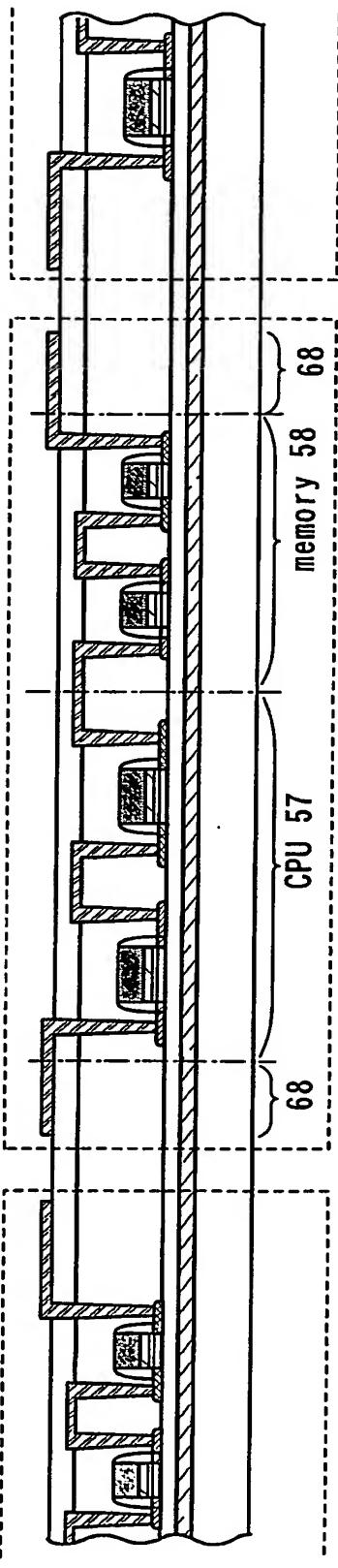
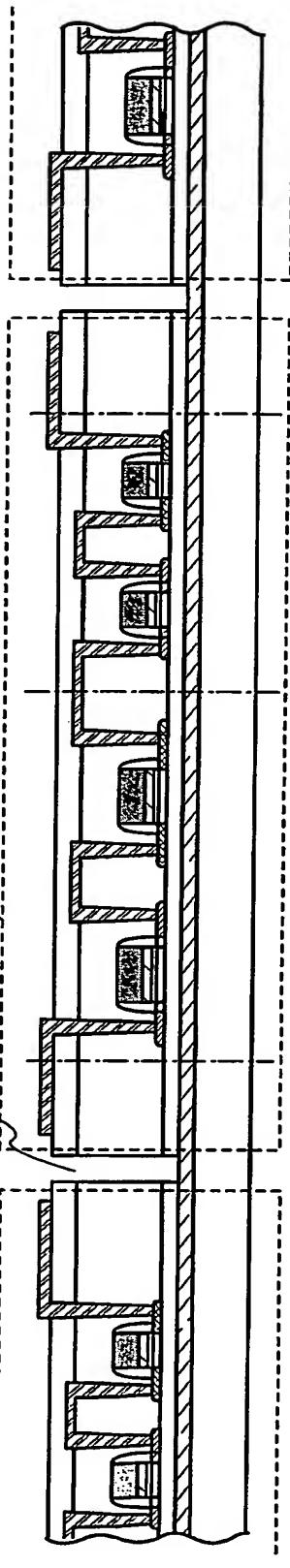
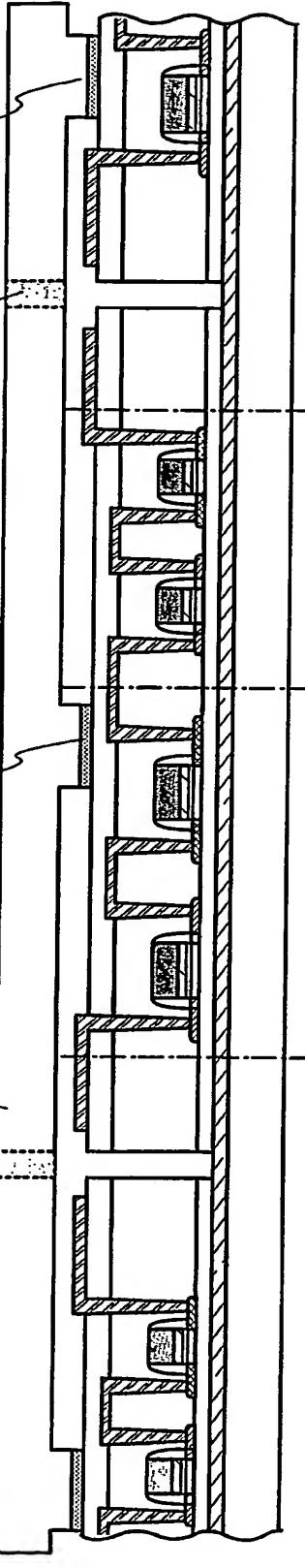


FIG. 9J forming thin film integrated circuit device**FIG. 9K forming groove** 70 **thin film integrated circuit portion** 69**FIG. 9L attaching jig** 72 **adhesive agent** 73 **jig (supporting substrate)** 74 **opening portion** 74 **protrusion** 71

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FIG. 10M introducing halogen fluoride

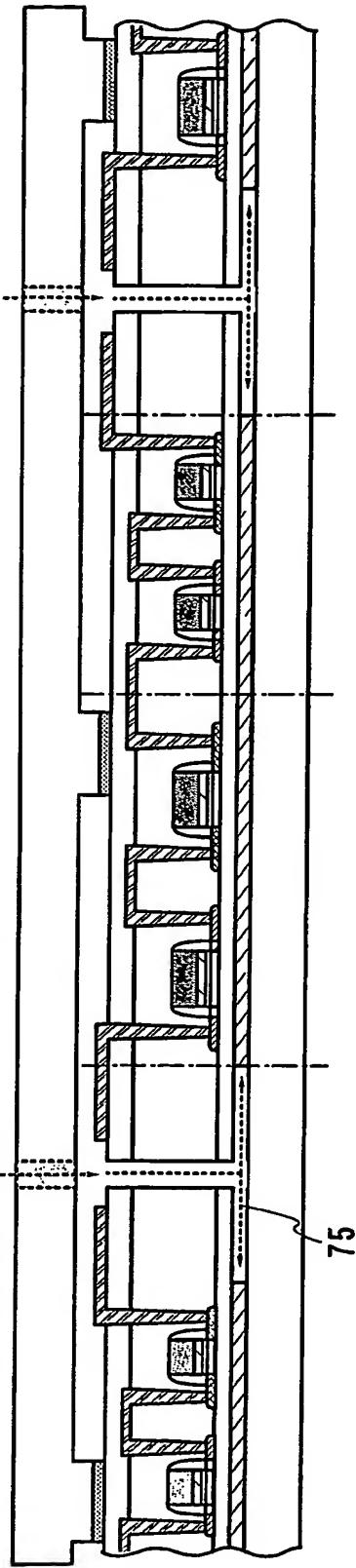


FIG. 10N separating substrate

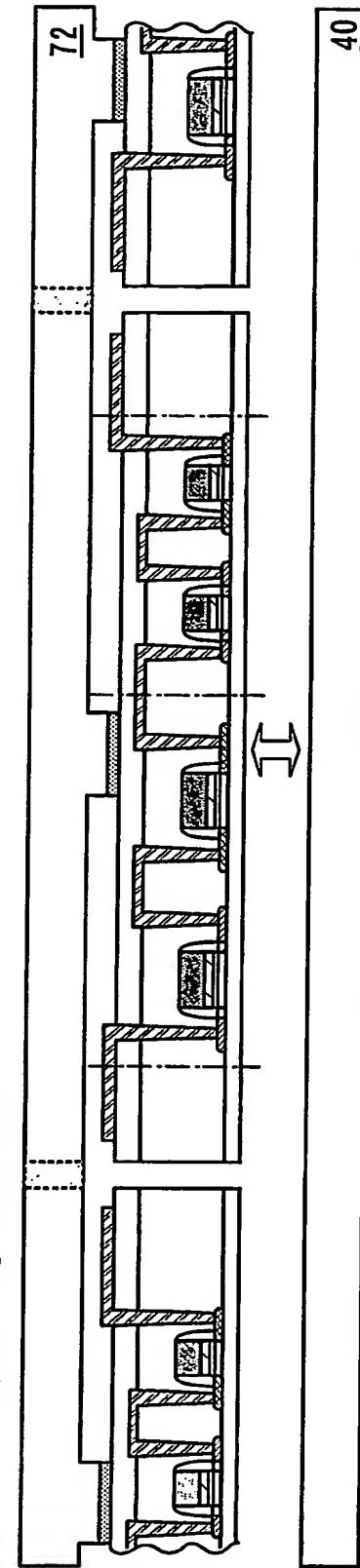
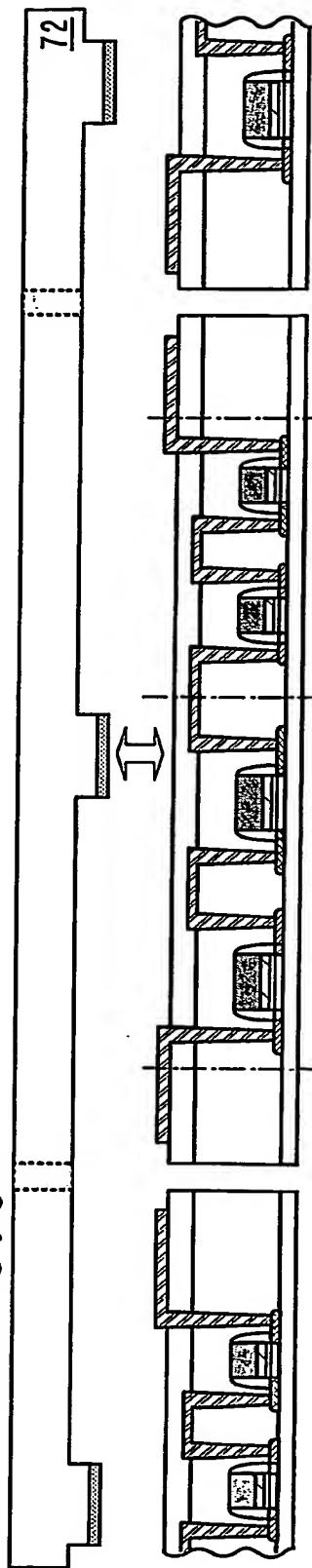


FIG. 10O detaching jig



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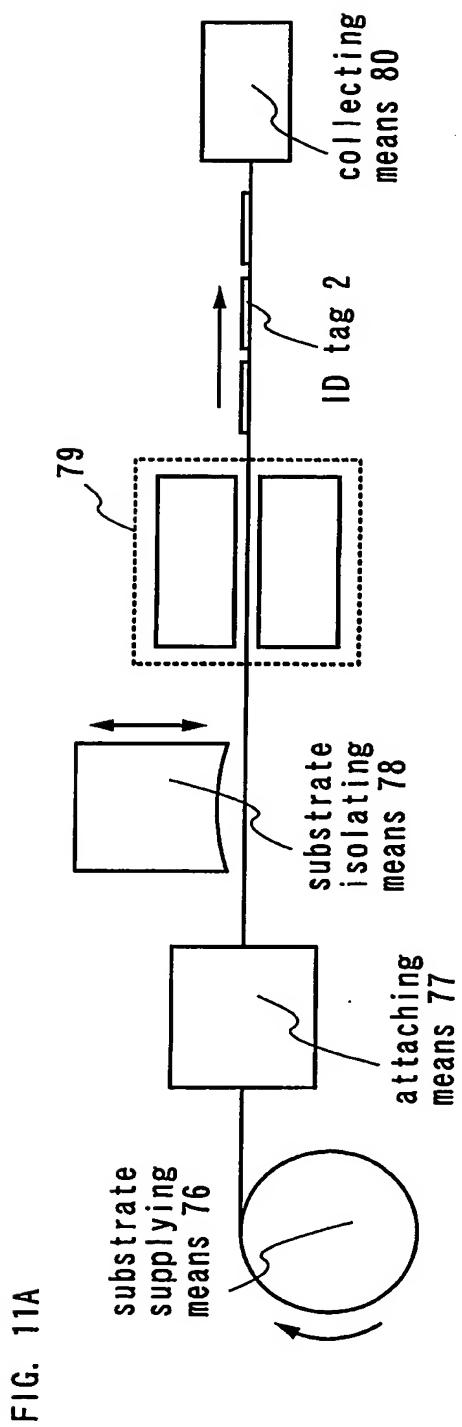
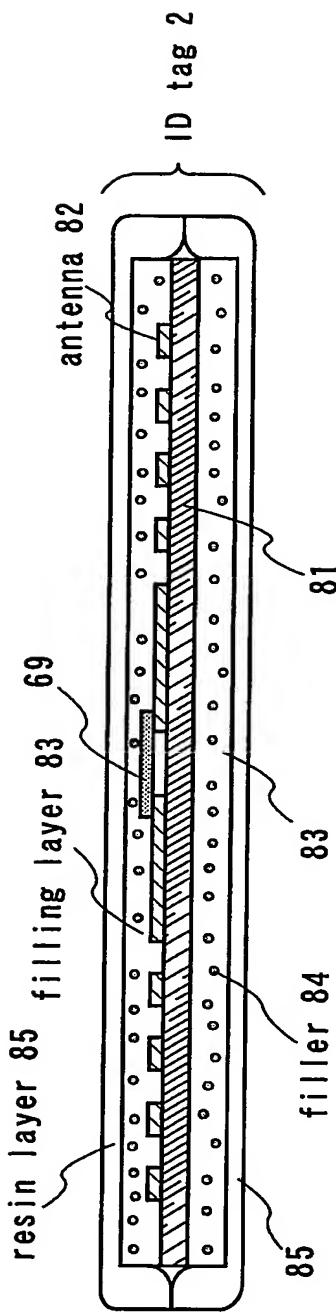
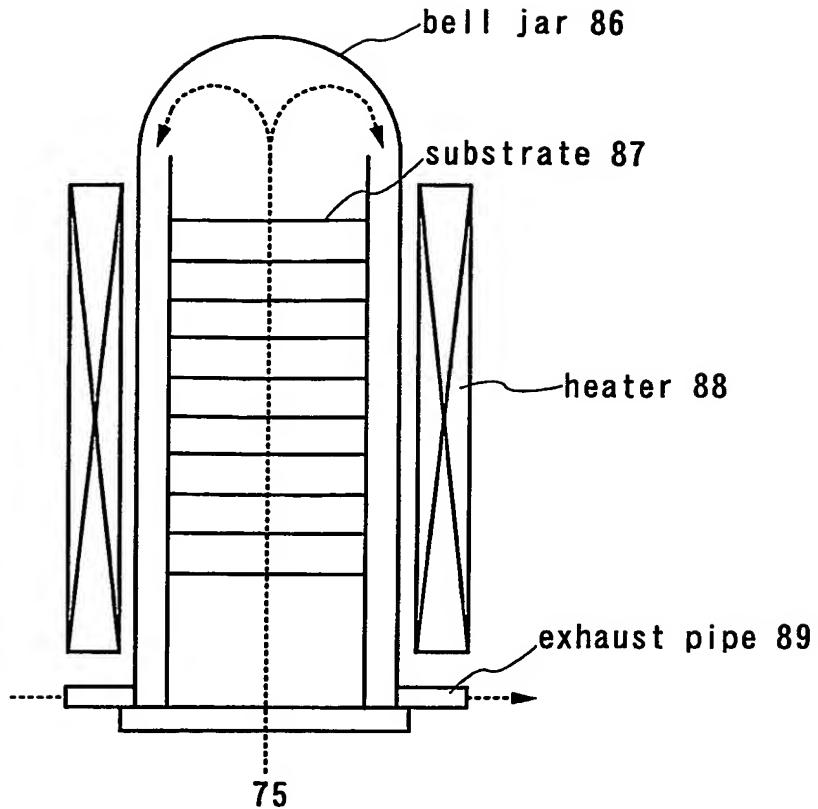


FIG. 11B magnified drawing of IDtag as a completed article



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FIG. 12



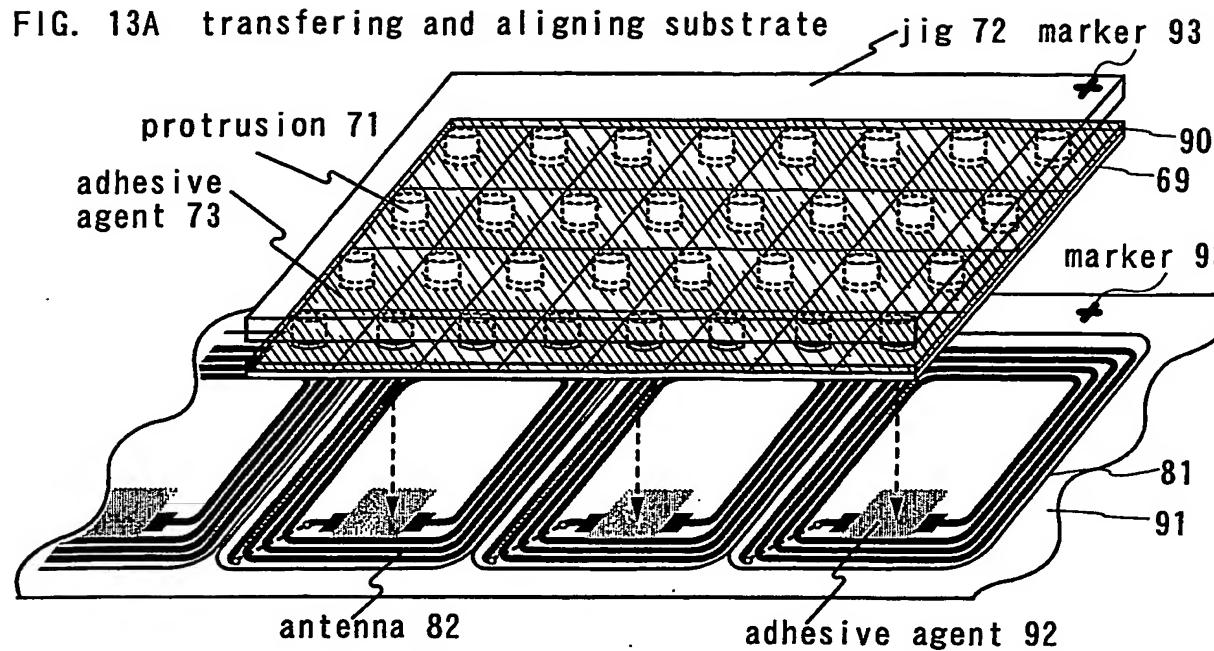


FIG. 13B attaching thin film integrated circuit portion

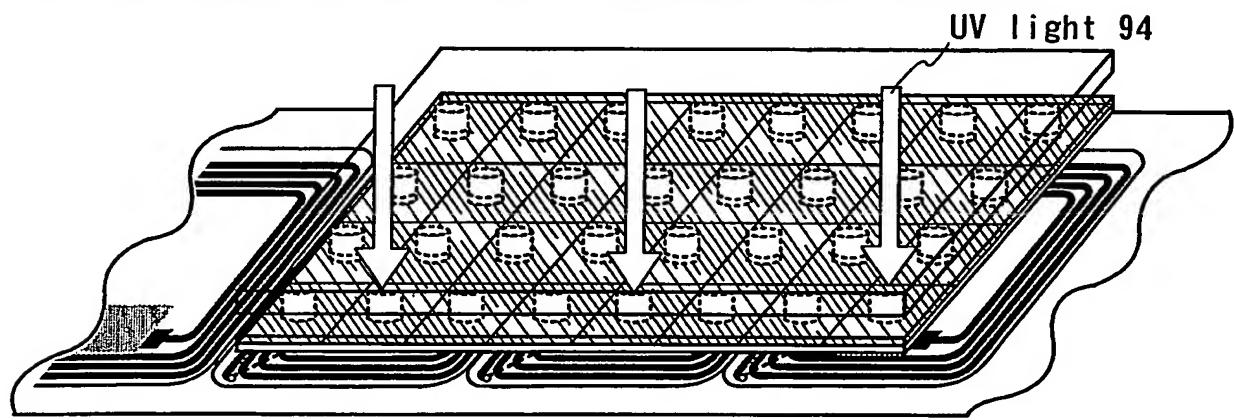
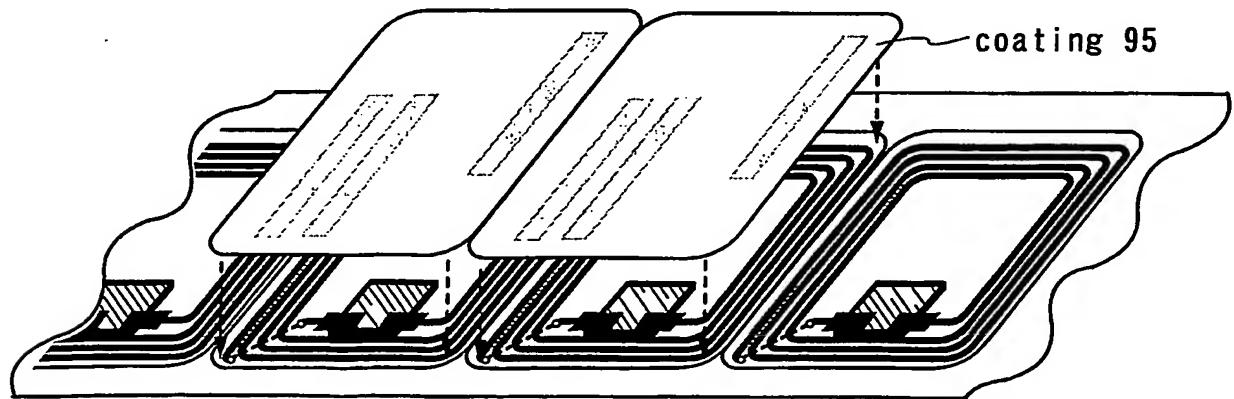


FIG. 13C covering by coating



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EXPLANATION OF REFERENCE

1. product, 2. ID tag, 3. package body, 4. resonance circuit portion, 5. R/W, 6. antenna portion, 7. display portion, 8. operation key, 9. computer, 10. database, 11. controller, 12. output interface, 13. input interface, 14. output antenna, 15. input antenna, 16. integrated circuit portion, 17. electromagnetic wave, 18. antenna coil, 19. capacitor, 20. input antenna, 21. output antenna, 22. input interface, 23. output interface, 24. rectification circuit, 25. demodulation circuit, 26. modulation circuit, 27. amplifier, 28. bus, 29. thin film integrated circuit portion, 30. CPU, 31. coprocessor, 32. ROM, 33. RAM, 34. nonvolatile memory, 35. suitcase, 36. price tag, 37. conveyer, 38. transportation vehicle, 39. resonance circuit portion, 40. substrate, 41. separation layer, 42. protective film, 43. island-like semiconductor film, 44. gate insulating film, 45. resist, 46. gate electrode, 47. resist, 48. impurity element, 49. low concentration impurity region, 50. resist, 51. impurity element, 52. p-type high concentration impurity region, 53. n-channel TFT, 54. p-channel TFT, 55. n-channel TFT, 56. p-channel TFT, 57. CPU, 58. memory, 59. insulating film, 60. sidewall, 61. resist, 62. impurity element, 63. n-type high concentration impurity region, 64. interlayer film, 65. protective film, 66. wiring, 67. connection wiring, 68. antenna connection portion, 69. thin film integrated circuit portion, 70. groove, 71. protrusion, 72. jig, 73. adhesive agent, 74. opening portion, 75. halogen fluoride gas, 76. substrate supplying means, 77. attaching means, 78. substrate isolating means, 79. laminating device, 80. collecting means, 81. inlet substrate, 82. antenna, 83. filling layer, 84. filler, 85. laminate resin layer, 86. bell jar, 87. substrate, 88. heater, 89. exhaust pipe, 90. protective film, 91. stage, 92. adhesive agent, 93. marker, 94. UV light, 95. coating, 201. antenna wiring, 202. antenna capacitor, 203. first capacitor means, 204. first diode, 205. second diode, 206. second capacitor means, 207. third diode, 208. third capacitor means, 209. switching element, 210. logic circuit, 211. amplifier, 212. clock generation circuit-decoder, 213. memory, 214. power supply circuit, 215. input-output circuit, 216. antenna circuit,